Heraeus

Electronics

C5909P

Conductor

Description

C5909P is a screen printable, gold paste designed as a hole plug in alumina substrates. The high solids loading allows for excellent filling properties. C5909P has low shrinkage, which allows for a complete fill of the through hole.

Key Features

- High solids loading Low shrinkage For use in a print process

This picture does not show the packaging of C5909Pand is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties	
Conductivity	≤ 25.0 milliohms/square at 25 um fired film thickness
Viscosity	350 – 450 Kcps, Brookfield HBTSC4 – 14 spindle and 6R cup at 10 rpm, 25 °C
Solids	94.5 ± 1.0 %
Alloy Ratio	100
Metal	Au

Recommended Processing Guide	
Printing Parameters	Stencil printing process 3 – 5 mil stencil thicknes
Drying Temperature	150 °C for 15 minutes
Process Temperature (TDS)	850 ℃ peak temperature Dwell time 8 – 12 minutes
Recommended Thinner	RV-372

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Warranty

6 months

Storage

Store in a dry location at 20°C-25°C

All changes are based on information displayed using the template data_sheet/HET/TFM/print_data_sheet.html.twig.
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